



## INFORMATION DISCLOSURE STATEMENT

Applicant : Lin, et al.  
 App. No : 10/807,128  
 Filed : March 24, 2004  
 For : OPTICAL INTERFERENCE DISPLAY  
 PANEL AND MANUFACTURING  
 METHOD THEREOF  
 Examiner : Unassigned  
 Art Unit : 3746

## CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

*August 30, 2006*  
 (Date)  
 Michael L. Fuller, Reg. No. 36,516

Mail Stop Amendment  
 Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified application is a PTO/SB/08 Equivalent listing 52 references to be considered by the Examiner. Also enclosed are 11 foreign patent references and/or non-patent literature as listed on the Information Disclosure Statement.

This Information Disclosure Statement is being filed before the receipt of a first Office Action on the merits, and presumably no fee is required. If a first Office Action on the merits was mailed before the mailing date of this Statement, the Commissioner is authorized to charge the fee set forth in 37 C.F.R. § 1.17(p) to Deposit Account No. 11-1410.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: *August 30, 2006*

By: *[Signature]*

Michael L. Fuller  
 Registration No. 36,516  
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 (619) 235-8550

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ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. *MC*

# INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Multiple sheets used when necessary)

SHEET 1 OF 3

Application No.	10/807,128
Filing Date	March 24, 2004
First Named Inventor	Lin, et al.
Art Unit	3746
Examiner	Unassigned
Attorney Docket No.	QCO.086A/IDC- 061118

## U.S. PATENT DOCUMENTS

Cite No.	Document Number Number - Kind Code (if known) Example: 1,234,567 B1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
1	4,074,480	02-21-1978	Burton	
2	4,956,619	09-11-1990	Hornbeck	
3	5,018,256	05-28-1991	Hornbeck	
4	5,099,353	03-24-1992	Hornbeck	
5	5,216,537	06-01-1993	Hornbeck	
6	5,244,707	09-14-1993	Shores	
7	5,401,983	03-28-1995	Jokerst, et al.	
8	5,653,662	12-29-1998	Watanabe	
9	5,939,785	08-17-1999	Klonis, et al.	
10	6,055,090	04-25-2000	Miles, et al.	
11	6,238,755	05-29-2001	Harvey et al.	
12	6,379,988	04-30-2002	Peterson, et al.	
13	6,447,126	09-10-2002	Hornbeck	
14	6,455,927	09-24-2002	Glenn, et al.	
15	6,465,355	10-15-2002	Horsley	
16	6,489,670	12-03-2002	Peterson, et al.	
17	6,495,895	12-17-2002	Peterson, et al.	
18	6,538,312	03-25-2003	Peterson, et al.	
19	6,603,182	08-05-2003	Low et al.	
20	6,661,084	12-09-2003	Peterson, et al.	
21	6,674,159	01-06-2004	Peterson, et al.	
22	2002-0056900	05-16-2002	Liu et al.	
23	2002-0075551	06-20-2002	Daneman	
24	2002-0160583	10-31-2002	Song	
25	2003-152872	08-14-2003	Miles, Mark	
26	2003-054588	03-20-2003	Patel, et al.	
27	2003-0062186	04-03-2003	Borason, et al.	
28	2003-0075794	04-24-2003	Felton, et al.	
29	2003-0108306	06-12-2003	Whitney et al.	

Examiner Signature

Date Considered

\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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(Multiple sheets used when necessary)		Examiner	Unassigned
SHEET 2 OF 3		Attorney Docket No.	QCO.086A/IDC- 061118

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	30	2003-0183916	10-02-2003	Heck et al.	
	31	2003-0184412	10-02-2003	Gorrell	
	32	2004-0061492	04-01-2004	Lopes, et al.	
	33	2004-0100677	05-27-2004	Huibers, et al.	
	34	2004-0140557	07-22-2004	Sun et al.	
	35	2004-0184133	09-23-2004	Su et al.	
	36	2005-0035699	02-17-2005	Tsai	
	37	2005-0036192	02-17-2005	Lin et al.	
	38	2005-0042117	02-24-2005	Lin	
	39	2005-0074919	04-07-2005	Patel	
	40	2005-0195462	09-08-2005	Lin	
	41	2005-0253283	11-17-2005	Dcamp et al.	

## FOREIGN PATENT DOCUMENTS

Examiner Initials	Cite No.	Foreign Patent Document Country Code-Number-Kind Code Example: JP 1234567 A1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear	T <sup>1</sup>
	42	WO 02/042716	05/30/2002	Microsensors		
	43	WO 03/026369	03-27-2003	Stafford, et al.		
	44	WO 05/114294	12-01-2005	Palmtree, et al.		
	45	WO 05/110914	11-24-2005	Kothari, et al.		
	46	WO 05/066596	07-21-2005	Honeywell		
	47	WO 99/41732	02-17-1999	Sarnoff Corporation		

## NON PATENT LITERATURE DOCUMENTS

Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>1</sup>
	48	MORAJA, et al. "Advanced Getter Solutions at Wafer Level to Assure High Reliability to the last Generations MEMS, IEEE Reliability Physics Symposium Proceedings, 2003 pp. 458-459.	
	49	LIANG, ZHI-HAO et al., "A Low Temperature Wafer-Level Hermetic MEMS Package Using UV Curable Adhesive", Electronic Components and Technology Conference, 2004 IEEE, pp. 1486-1491.	

Examiner Signature	Date Considered
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T<sup>1</sup> - Place a check mark in this area when an English language translation is attached.

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## NON PATENT LITERATURE DOCUMENTS

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	50	SPARKS, et al. Chip-Level Vacuum Packaging of Micromachines Using NanoGetters, IEEE Transactions on Advanced Packaging, Vol. 26 Issue 3, August 2003, pgs. 277-282.	
	51	EP Search Report for EP patent No. 05255700.6 – 2217.	
	52	EP Search Report for EP patent No. 05255684.2 – 2217.	

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Examiner Signature	/Michael Caley/	Date Considered	07/10/2008
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